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**Sestavi plošč tiskanih vezi - 10-2.del: Smernice za določanje parametrov spajanja pri lasersko podprtem spajanju med polprevodniškim čipom in substratom**

Circuit board assemblies - Part 10-2 : Guideline for Establishing Bonding Parameters in Laser-Assisted Bonding between Semiconductor Chip and Substrate

Sample Document

**Ta slovenski standard je istoveten z: prEN IEC 61191-10-2:2026**

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# 91/2120/CDV

## COMMITTEE DRAFT FOR VOTE (CDV)

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|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------|
| IEC TC 91 : ELECTRONICS ASSEMBLY TECHNOLOGY                                                                                                                                                                                                                                                                                                                                             |                                                                    |
| SECRETARIAT:<br>Japan                                                                                                                                                                                                                                                                                                                                                                   | SECRETARY:<br>Mr Osamu IKEDA                                       |
| OF INTEREST TO THE FOLLOWING COMMITTEES:<br>TC 40,TC 47,SC 47A,SC 47D                                                                                                                                                                                                                                                                                                                   | HORIZONTAL FUNCTION(S):                                            |
| ASPECTS CONCERNED:                                                                                                                                                                                                                                                                                                                                                                      |                                                                    |
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TITLE:

**Circuit board assemblies - Part 10-2 : Guideline for Establishing Bonding Parameters in Laser-Assisted Bonding between Semiconductor Chip and Substrate**

PROPOSED STABILITY DATE: 2032

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

## CIRCUIT BOARD ASSEMBLIES–

**Part 10-2: Guideline for Establishing Bonding Parameters in Laser-Assisted Bonding between Semiconductor Chip and Substrate**

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The text of this standard is based on the following documents:

| Draft      | Report on voting |
|------------|------------------|
| 91/XX/FDIS | 91/XX/RVD        |

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.